

**Student Name:** \_\_\_\_\_

**ELN247 Project Evaluation Rubric**

	<b>150</b>	<b>100</b>	<b>50</b>	<b>0</b>	<b>Total</b>
<b>Professionalism</b>	Student always conducted themselves in a professional manner throughout the semester. Student attended all required class sessions, pursued objectives with due diligence, worked independently, and maintained composure during times of frustration.	Student usually conducted themselves in a professional manner throughout the semester. Student attended most required class sessions, usually pursued objectives with due diligence, usually worked independently, and usually maintained composure during times of frustration.	Student sometimes conducted themselves in a professional manner throughout the semester. Student attended some of the required class sessions, sometimes pursued objectives with due diligence, sometimes worked independently, and usually maintained composure during times of frustration.	Student inconsistently conducted themselves in a professional manner throughout the semester. Student was often absent for required class sessions, pursued objectives with due diligence, often required assistance, and did not always maintain composure during times of frustration.	
<b>Acceptance Test</b>	Project is in working order and meets all test requirements. Lab notebook is complete. A test procedure and a product specification sheet are included.	Project is in good working order and meets most test requirements. Lab notebook is mostly complete. A test procedure and a product specification sheet are included with some elements missing.	Project is in marginal working order and meets some test requirements. Lab notebook, test procedure, and/or specification sheet are marginally complete.	Project is not in working order. Few or no test requirements are met. Lab notebook, test procedure, and/or specification sheet poorly done or missing.	
	<b>200</b>	<b>140</b>	<b>80</b>	<b>20</b>	
<b>Workmanship</b>	All workmanship is of a professional quality. Solder joints are proper and clean, wires are dressed well, machining is clean, and controls are labeled. Software is clean, wellstructured, labeled, and stable.	Workmanship is of a reasonable quality. Most solder joints are proper and clean, most wires are dressed well, most machining is clean, and most controls are labeled. Software is reasonably clean, well-structured, labeled, and stable.	Workmanship is of a marginal quality. Few solder joints are proper and clean, few wires are dressed well, machining is rough, and controls may not be labeled. Software is marginally clean, well-structured, labeled, and stable.	Workmanship is not of a poor quality. Solder joints are poor, wires are loose, machining is sloppy, and controls are not labeled. Software is not clean, well-structured, labeled, and/or stable.	
	<b>100</b>	<b>70</b>	<b>40</b>	<b>10</b>	
<b>Complexity Factor</b>	Project uses a student made PC Board, utilizes state of the art circuitry, requires a high number of components and parts ordered by the student, and requires extensive acceptance testing.	Project uses a premade PC Board, uses parts ordered by the student, and testing is moderately challenging.	Project may be built from a kit, few parts are required, testing is prescribed or minimally challenging.	Project is built from a kit, no new components are used, few parts are required, testing is minimal.	
<b>Meeting Deadlines</b>	All deadlines for schedules, mid-term design review, final product, and lab report met on time	All deadlines for schedules, mid-term design review, final product, and lab report met with no more than one week of slippage	All deadlines for schedules, mid-term design review, final product, and lab report met with no more than two weeks of slippage	Deadlines for schedules, mid-term design review, final product, and lab report not met.	
<b>Written Score (From Rubric)</b>					
<b>Oral Score (From Rubric)</b>					

<b>Grand Total</b>					
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